

## High Precision Wraparound - High Temperature (230 °C) Thin Film Chip Resistors



### INTRODUCTION

For applications such as down hole applications, the need for parts able to withstand very severe conditions (temperature as high as 215 °C powered or up to 230 °C un-powered) has leaded Vishay Sfernice to push out the limit of the thin film technology.

Designers might read the application note: Power Dissipation Considerations in High Precision Vishay Sfernice Thin Film Chip Resistors and Arrays (P, PRA etc...) (High Temperature Application) [www.vishay.com/doc?53047](http://www.vishay.com/doc?53047) in conjunction with this datasheet to help them to properly design their PCBs and get the best performances of the PHT. Vishay Sfernice R&D engineers will be willing to support any customer design considerations.

### FEATURES

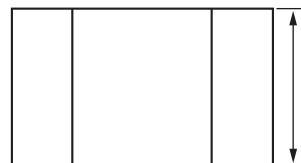
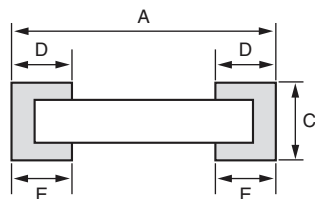
- Operating temperature range:  
- 55 °C; + 215 °C
- Storage temperature: - 55 °C; + 230 °C
- Gold terminations (< 1 μm thick)
- 4 sizes available (0603, 0805, 1206, 2010) - other sizes upon request
- Temperature coefficient down to 25 ppm  
(- 55 °C; + 215 °C)
- Tolerance down to 0.05 %
- Load life stability: 0.5 % max after 1000 h at 215 °C (ambient) at Pn
- SMD wraparound
- Compliant to RoHS directive 2002/95/EC



**RoHS**  
COMPLIANT

**GREEN**  
[5-2009]\*\*

### DIMENSIONS in millimeters (inches)



CASE SIZE	A		B		C	D/E	
	MAX. TOL. + 0.152 (+ 0.006)	MIN. TOL. - 0.152 (- 0.006)	MAX. TOL. + 0.127 (+ 0.005)	MIN. TOL. - 0.127 (- 0.005)		NOMINAL	TOLERANCE
	NOMINAL		NOMINAL				
0603	1.52 (0.060)		0.85 (0.033)		0.5 (0.02) ± 0.127 (0.005)	0.38 (0.015)	0.13 (0.005)
0805	1.91 (0.075)		1.27 (0.050)			0.40 (0.016)	
1206	3.06 (0.120)		1.60 (0.063)			0.48 (0.019)	
2010	5.08 (0.200)		2.54 (0.100)				

\*\* Please see document "Vishay Material Category Policy": [www.vishay.com/doc?99902](http://www.vishay.com/doc?99902)

**SUGGESTED LAND PATTERN** (to IPC-7351A)


CHIP SIZE	DIMENSIONS (in millimeter)		
	Z <sub>max.</sub>	G <sub>min.</sub>	X <sub>max.</sub>
0603	2.37	0.35	0.98
0805	2.76	0.74	1.40
1206	3.91	1.85	1.73
2010	5.93	3.71	2.67

STANDARD ELECTRICAL SPECIFICATIONS		
TEST	SPECIFICATIONS	CONDITIONS
Series	0603, 0805, 1206, 2010	
Ohmic Range <sup>(1)</sup>	10R to 7M6 (depending on series)	
Temperature Coefficient <sup>(2)</sup>	25 ppm/°C, 50 ppm/°C, 100 ppm/°C	- 55 °C; + 215 °C
Tolerance	0.05 %, 0.1 %, 0.5 %, 1 %	
Power Rating (P <sub>n</sub> ) <sup>(3)</sup>	12.5 mW to 100 mW	215 °C
Operating Temperature Range	- 55 °C; + 215 °C	
Limiting Voltage <sup>(3)</sup>	75 V to 300 V	
Load Life Stability	0.50 %	1000 h/215 °C (ambient) at P <sub>n</sub>
Storage Temperature Range	- 55 °C; + 230 °C	
Shelf Life Stability	0.7 % typ. (1 % max.)	8000 h/230 °C

**Notes**

<sup>(1)</sup> Please refer to table 3 for TCR versus ohmic values

<sup>(2)</sup> See table 2

<sup>(3)</sup> See table 1

**Caution:**

Performances obtained with following mounting conditions:

PCB: Polyimide

Solder paste: PbSnAg (93.5/5/1.5)

TABLE 1		
SIZE	POWER RATING <sup>(1)</sup>	LIMITING VOLTAGE
0603	12.5 mW	75 V
0805	20 mW	150 V
1206	33 mW	200 V
2010	100 mW	300 V

**Note**

<sup>(1)</sup> For power handling improvement, please refer to application note 53047: Power Dissipation Considerations in High Precision Vishay Sfernice Thin Film Chip Resistors and Arrays (High Temperature Applications) [www.vishay.com/doc?/53047](http://www.vishay.com/doc?/53047) and consult Vishay Sfernice

TABLE 2 - TEMPERATURE COEFFICIENT		
Y	10 ppm/°C	- 55 °C; + 155 °C
	25 ppm/°C	- 55 °C; + 215 °C
E	25 ppm/°C	- 55 °C; + 155 °C
	50 ppm/°C	- 55 °C; + 215 °C
H	50 ppm/°C	- 55 °C; + 155 °C
	100 ppm/°C	- 55 °C; + 215 °C

TABLE 3				
SERIES	OHMIC RANGE <sup>(2)</sup>			
	CT: Y		CT: E/H	
	Min.	Max.	Min.	Max.
0603	39 Ω	320K	10 Ω	320K
0805	39 Ω	511K	10 Ω	725K
1206	39 Ω	1M8	10 Ω	2M7
2010	39 Ω	5M	10 Ω	7M6

**Note**

<sup>(2)</sup> Best tolerance possible:  
 0.5 %: 10 Ω to < 20 Ω  
 0.1 %: 20 Ω to < 39 Ω  
 0.05 %: 39 Ω to max. value

**PHT STABILITY CURVE**



**Note**

• Stability will be dependent on resistivity of resistor. Above curves are worst case.

MECHANICAL SPECIFICATIONS	
Substrate	Alumina
Resistive Element	Nichrome (NiCr)
Passivation	Silicon nitride (Si <sub>3</sub> N <sub>4</sub> )
Protection	Epoxy + Silicone
Terminations	Gold (< 1 μm) over nickel barrier

**Note**

- For other terminations, please consult

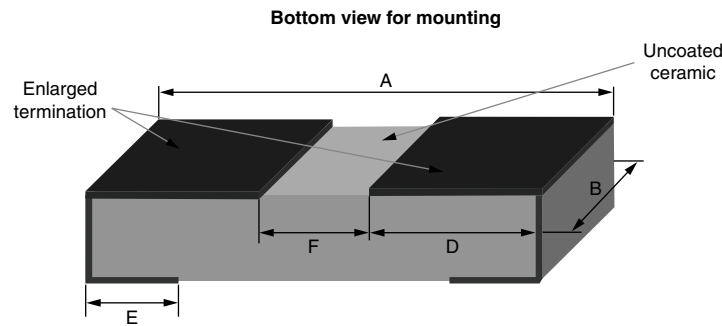
**POPULAR OPTIONS**

It is recommended to consult Vishay Sfernice for availability first.

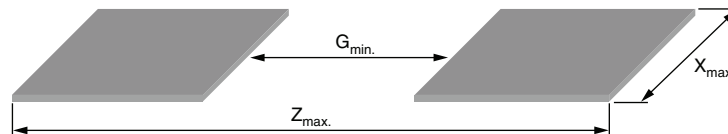
**Option: Enlarged terminations:**

For stringent and special power dissipation requirements, the thermal resistance between the resistive layer and the solder joint can be reduced using enlarged terminations chip resistors which are soldered on large and thick copper pads acting as heatsink (see application note: 53048 Power Dissipation in High Precision Vishay Sfernice Chip Resistors and Arrays (P Thin Film, PRA Arrays, CHP Thick Film) [www.vishay.com/doc?53048](http://www.vishay.com/doc?53048)).

Option to order: 0063 (applies to size 1206/2010).

**DIMENSIONS** (Option 0063) in millimeters


CASE SIZE	A	B	E	D	F		
	MAX. TOL. + 0.152 MIN. TOL. - 0.152	MAX. TOL. + 0.127 MIN. TOL. - 0.127	MAX. TOL. + 0.13 MIN. TOL. - 0.13	MAX. TOL. + 0.13 MIN. TOL. - 0.13	NOMINAL	MIN.	MAX.
	NOMINAL	NOMINAL	NOMINAL	NOMINAL			
1206	3.06	1.60	0.40	1.215	0.63	0.50	0.76
2010	5.08	2.54	0.48	2.25			

**SUGGESTED LAND PATTERN** (Option 0063)


CHIP SIZE	DIMENSIONS (in millimeter)		
	Z <sub>max.</sub>	G <sub>min.</sub>	X <sub>max.</sub>
1206	3.91	0.50	1.73
2010	5.93		2.67

Vishay Sfernice High Precision Wraparound - High Temperature (230 °C)  
Thin Film Chip Resistors

**PACKAGING**

ESD packaging available: waffle-pack, and plastic tape and reel (low conductivity). Paper tape available upon request (ESD only).

SIZE	MOQ	NUMBER OF PIECES PER PACKAGE			TAPE WIDTH
		WAFFLE PACK 2" x 2"	TAPE AND REEL		
			MIN.	MAX.	
0603	100	100	100	4000	8 mm
0805					
1206		140	2000	8 mm <sup>(1)</sup>	
2010		60			

**Note**  
<sup>(1)</sup> 12 mm on request

**PACKAGING RULES**

**Waffle Pack**

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered exceeds maximum quantity of a single waffle pack, the waffle packs are stacked up on the top of each other and closed by one single cover.

**To get “not stacked up” waffle pack in case of ordered quantity > maximum number of pieces per package: Please consult Vishay Sfernice for specific ordering code**

**Tape and Reel**

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered is between the MOQ and the maximum reel capacity, only one reel is provided.

**When several reels are needed for ordered quantity within MOQ and maximum reel capacity: Please consult Vishay Sfernice for specific ordering code**

GLOBAL PART NUMBER INFORMATION																	
Global Part Numbering: PHT1206Y1001BGT063																	
P	H	T	1	2	0	6	Y	1	0	0	1	B	G	T	0	6	3
GLOBAL MODEL	SIZE	TCR	VALUE					TOLERANCE	TERMINATION	PACKAGING		OPTION					
PHT	0603 0805 1206 2010	Y E H	The first three digits are significant figures and the last digit specifies the number of zeros to follow, R designates decimal point  10R0 = 10 Ω 3901 = 3900 Ω 1004 = 1 MΩ					W = 0.05 % B = 0.1 % D = 0.5 % F = 1 %	G = Gold N = Tin/silver <sup>(2)</sup>	T = Tape and reel Blank = Waffle pack		Leave blank if no option					

**Note**  
<sup>(2)</sup> For usage at temperatures up to 200 °C maximum N (tin/silver termination are available upon request)



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